

*Amendments to the Claims*

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-26. (canceled)

27. (currently amended) A thermosyphon for enhancing cooling of electronic systems, the thermosyphon receiving heat from a heat-dissipating component and comprising:

a central evaporator in contact with the heat-dissipating component, wherein the central evaporator comprises:

a first plate having an interior major surface and an exterior major surface;

a second plate, generally parallel to, spaced from, and similar in planar dimension to the first plate, having an interior major surface and an exterior major surface, the interior major surface opposing the interior major surface of the first plate, with a central parallel plane passing through the space therebetween, the second plate exterior major surface in contact with at least a portion of the component and extending outside the limits of that portion of the component, wherein the interior major surfaces define an evaporator volume;

a condenser in fluid communication with and extending around the periphery of the evaporator, wherein the condenser comprises:

a first wall extending from each evaporator plate, the first wall having an interior surface, a proximate edge and a distal edge, the proximate edge sealingly joined to the periphery of the respective plate, and the first wall extending perpendicularly from the entire periphery of each plate in a direction away from the central plane for a substantially constant distance, whereby the distal edge is substantially parallel to the plates;

a second wall extending from each respective first wall, each second wall having an interior surface, a proximate edge and a distal edge, the proximate edge of each second wall sealingly joined to and extending perpendicularly from the

entire distal edge of the adjoining first wall in a direction away from the evaporator volume; and

a third wall extending from each respective second wall, each third wall having an interior surface, a proximate edge and a distal edge, the proximate edge of each third wall sealingly joined to and extending perpendicularly from the entire distal edge of the adjoining second wall such that the distal edges of the respective third walls abut and sealingly join at the central plane, whereby the interior surfaces of the first, second, and third walls define a condenser volume in fluid communication with the evaporator volume,

a liquid coolant partially filling the condenser and substantially filling the evaporator; and

means for cooling the condenser,

wherein at all orientations the evaporator is substantially full of liquid coolant,

wherein the planar shapes of the evaporator and condenser peripheries are substantially rectangular, and

~~A thermosyphon as recited in claim 26,~~ wherein the cross-sectional shape of the condenser along an edge of the evaporator and perpendicular to the central plane is generally rectangular, the condenser is generally symmetric about the central plane, and the dimensions of the evaporator and condenser approximately satisfy the following relationship, where  $H_B$  is the height of the condenser,  $H_E$  is the distance between the interior surface of the second plate and the interior surface of the first plate,  $L_B$  is the distance that the condenser extends from the periphery of the evaporator, perpendicular to the respective edge of the evaporator,  $L_E$  is the length of the evaporator along one edge, and  $W_E$  is the length of the evaporator along an edge perpendicular to the edge having length  $L_E$ :

$$H_B/H_E = (2L_B + L_E + W_E)/L_E.$$

28. (currently amended) The A thermosyphon as recited in claim 27, wherein when the central plane is horizontal, within the condenser limits the surface of the liquid coolant is ap-

proximately a distance of  $(H_B + H_E)/2$  from the interior surface of the plate that is beneath the coolant.

29. (canceled)

30. (currently amended) A thermosyphon for enhancing cooling of electronic systems, the thermosyphon receiving heat from a heat-dissipating component and comprising:

a central evaporator in contact with the heat-dissipating component, wherein the central evaporator comprises:

a first plate having an interior major surface and an exterior major surface;

a second plate, generally parallel to, spaced from, and similar in planar dimension to the first plate, having an interior major surface and an exterior major surface, the interior major surface opposing the interior major surface of the first plate, with a central parallel plane passing through the space therebetween, the second plate exterior major surface in contact with at least a portion of the component and extending outside the limits of that portion of the component, wherein the interior major surfaces define an evaporator volume;

a condenser in fluid communication with and extending around the periphery of the evaporator, wherein the condenser comprises:

a first wall extending from each evaporator plate, the first wall having an interior surface, a proximate edge and a distal edge, the proximate edge sealingly joined to the periphery of the respective plate, and the first wall extending perpendicularly from the entire periphery of each plate in a direction away from the central plane for a substantially constant distance, whereby the distal edge is substantially parallel to the plates;

a second wall extending from each respective first wall, each second wall having an interior surface, a proximate edge and a distal edge, the proximate edge of each second wall sealingly joined to and extending perpendicularly from the

entire distal edge of the adjoining first wall in a direction away from the evaporator volume; and

a third wall extending from each respective second wall, each third wall having an interior surface, a proximate edge and a distal edge, the proximate edge of each third wall sealingly joined to and extending perpendicularly from the entire distal edge of the adjoining second wall such that the distal edges of the respective third walls abut and sealingly join at the central plane, whereby the interior surfaces of the first, second, and third walls define a condenser volume in fluid communication with the evaporator volume,

a liquid coolant partially filling the condenser and substantially filling the evaporator; and

means for cooling the condenser,

wherein at all orientations the evaporator is substantially full of liquid coolant,

wherein the planar shapes of the evaporator and condenser peripheries are substantially square, and

A thermosyphon as recited in claim 29, wherein the cross-sectional shape of the condenser along an edge of the evaporator and perpendicular to the central plane is generally rectangular, the condenser is generally symmetric about the central plane, and the dimensions of the evaporator and condenser approximately satisfy the following relationship, where  $H_B$  is the height of the condenser,  $H_E$  is the distance between the interior surface of the second plate and the interior surface of the first plate,  $L_B$  is the distance that the condenser extends from the periphery of the evaporator, perpendicular to the respective edge of the evaporator, and  $L_E$  is the length of the evaporator along each edge:

$$H_B/H_E = 2(1 + L_B/L_E).$$

31. (currently amended) The A thermosyphon as recited in claim 30, wherein when the central plane is horizontal, within the condenser limits the surface of the liquid coolant is approximately a distance of  $(H_B + H_E)/2$  from the interior surface of the plate that is beneath the coolant.

32-33. (canceled)

34. (currently amended) A thermosyphon for enhancing cooling of electronic systems, the thermosyphon receiving heat from a heat-dissipating component and comprising:

a central evaporator in contact with the heat-dissipating component, wherein the central evaporator comprises:

a first plate having an interior major surface and an exterior major surface;

a second plate, generally parallel to, spaced from, and similar in planar dimension to the first plate, having an interior major surface and an exterior major surface, the interior major surface opposing the interior major surface of the first plate, with a central parallel plane passing through the space therebetween, the second plate exterior major surface in contact with at least a portion of the component and extending outside the limits of that portion of the component, wherein the interior major surfaces define an evaporator volume;

a condenser in fluid communication with and extending around the periphery of the evaporator, wherein the condenser comprises:

a first wall extending from each evaporator plate, the first wall having an interior surface, a proximate edge and a distal edge, the proximate edge sealingly joined to the periphery of the respective plate, and the first wall extending perpendicularly from the entire periphery of each plate in a direction away from the central plane for a substantially constant distance, whereby the distal edge is substantially parallel to the plates;

a second wall extending from each respective first wall, each second wall having an interior surface, a proximate edge and a distal edge, the proximate edge of each second wall sealingly joined to and extending perpendicularly from the entire distal edge of the adjoining first wall in a direction away from the evaporator volume; and

a third wall extending from each respective second wall, each third wall having an interior surface, a proximate edge and a distal edge, the proximate edge of each third wall sealingly joined to and extending perpendicularly from the entire distal edge of the adjoining second wall such that the distal edges of the respective third walls abut and sealingly join at the central plane, whereby the interior surfaces of the first, second, and third walls define a condenser volume in fluid communication with the evaporator volume,  
a liquid coolant partially filling the condenser and substantially filling the evaporator; and  
means for cooling the condenser,  
wherein at all orientations the evaporator is full of liquid coolant,  
wherein the planar shapes of the evaporator and condenser peripheries are substantially circular,  
and  
A thermosyphon as recited in claim 33; wherein the cross-sectional shape of the condenser along the condenser radius and perpendicular to the central plane is generally rectangular, the condenser is generally symmetric about the central plane, and the dimensions of the evaporator and condenser approximately satisfy the following relationships, where  $H_B$  is the height of the condenser,  $H_E$  is the distance between the interior surface of the second plate and the interior surface of the first plate,  $R_B$  is the radius of the condenser as measured from the center of the evaporator to the outer limit of the condenser, and  $R_E$  is the radius of the evaporator, and when the central plane is vertical,  $\phi$  is the angle away from vertical of a line formed by the condenser radius when the outer endpoint of the condenser radius intersects the surface of the liquid coolant that fills the evaporator:

$$\phi = \frac{\pi}{2} \left( 1 - \left( \frac{R_E}{R_B} \right)^2 \right) \left( 1 - \frac{H_E}{H_B} \right) + \frac{R_E}{R_B} \sqrt{1 - \left( \frac{R_E}{R_B} \right)^2}$$

$$\phi = \cos^{-1} \left( \frac{R_E}{R_B} \right)$$

35. (currently amended) The A thermosyphon as recited in claim 34, wherein when the central plane is horizontal, on the surface of the liquid coolant is approximately a distance of  $(H_B + H_E)/2$  from the interior surface of the plate that is beneath the coolant.

36. (canceled)

37. (currently amended) A thermosyphon for enhancing cooling of electronic systems, the thermosyphon receiving heat from a heat-dissipating component and comprising:

a central evaporator in contact with the heat-dissipating component, wherein the central evaporator comprises:

a first plate having an interior major surface and an exterior major surface;

a second plate, generally parallel to, spaced from, and similar in planar dimension to the first plate, having an interior major surface and an exterior major surface, the interior major surface opposing the interior major surface of the first plate, with a central parallel plane passing through the space therebetween, the second plate exterior major surface in contact with at least a portion of the component and extending outside the limits of that portion of the component, wherein the interior major surfaces define an evaporator volume;

a condenser in fluid communication with and extending around the periphery of the evaporator, wherein the condenser comprises:

a first wall extending from each evaporator plate, the first wall having an interior surface, a proximate edge and a distal edge, the proximate edge sealingly joined to the periphery of the respective plate, and the first wall extending perpendicularly from the entire periphery of each plate in a direction away from the central plane for a substantially constant distance, whereby the distal edge is substantially parallel to the plates;

a second wall extending from each respective first wall, each second wall having an interior surface, a proximate edge and a distal edge, the proximate edge of each second wall sealingly joined to and extending perpendicularly from the

entire distal edge of the adjoining first wall in a direction away from the evaporator volume; and

a third wall extending from each respective second wall, each third wall having an interior surface, a proximate edge and a distal edge, the proximate edge of each third wall sealingly joined to and extending perpendicularly from the entire distal edge of the adjoining second wall such that the distal edges of the respective third walls abut and sealingly join at the central plane, whereby the interior surfaces of the first, second, and third walls define a condenser volume in fluid communication with the evaporator volume,

a liquid coolant partially filling the condenser and substantially filling the evaporator; and

means for cooling the condenser,

wherein at all orientations the evaporator is full of liquid coolant,

wherein the planar shapes of the evaporator and condenser peripheries are substantially square, and

~~A thermosyphon as recited in claim 36,~~ wherein the thermosyphon approximately satisfies the following relationships, where  $H_B$  is the height of the condenser,  $H_E$  is the distance between the interior surface of the second plate and the interior surface of the first plate,  $L_B$  is the distance that the condenser extends from the periphery of the evaporator, perpendicular to the respective edge of the evaporator,  $L_E$  is the length of the evaporator along each edge,  $\theta$  is an angle between two parallel edges of the condenser planar limits and horizontal when the central plane is vertically oriented and surface of the coolant is at the uppermost point of the evaporator,  $\theta^*$  is an angle between two parallel edges of the condenser planar limits and horizontal when the central plane is vertically oriented and surface of the coolant is at the uppermost point of the evaporator and at the second highest corner of the condenser:

$$\theta^* = \tan^{-1} \left( \frac{L_B}{L_B + L_E} \right);$$

for  $0 \leq \theta \leq \theta^*$ ;



$$\frac{H_B}{H_E} = \frac{2 \left( 1 + \frac{L_B}{L_E} \right) \frac{L_B}{L_E}}{\frac{L_B}{L_E} + \left( \frac{1}{2} + \frac{L_B}{L_E} \right) \tan \theta}; \text{ and}$$

for  $\theta^* \leq \theta \leq 45^\circ$ :

$$\frac{H_B}{H_E} = \frac{1 + \frac{L_B}{L_E}}{1 + \frac{1}{2} \left\{ 1 - \frac{1}{2} (\tan \theta + \cot \theta) \right\} \frac{L_B}{L_E}}.$$

38. (currently amended) The A thermosyphon as recited in claim 37, wherein when the central plane is horizontal, within the condenser limits the surface of the liquid coolant is approximately a distance of  $(H_B + H_E)/2$  from the interior surface of the plate that is beneath the coolant.

39-46. (canceled)